



Material Content Data Sheet



Sales Product Name		IPB014N06N		Issued		27. September 2017		
MA#		MA000965710						
Package		PG-TO263-7-3		Weight*		1552.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	26.819	1.73	1.73	17274	17274
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		517	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		155	
	non noble metal	copper	7440-50-8	801.714	51.65	51.72	516404	517076
wire	non noble metal	aluminium	7429-90-5	12.139	0.78	0.78	7819	7819
encapsulation	organic material	carbon black	1333-86-4	8.376	0.54		5395	
	plastics	epoxy resin	-	92.138	5.93		59349	
	inorganic material	silicondioxide	60676-86-0	457.900	29.49	35.96	294945	359689
leadfinish	non noble metal	tin	7440-31-5	12.317	0.79	0.79	7934	7934
plating	non noble metal	nickel	7440-02-0	0.269	0.02		173	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	173
solder	noble metal	silver	7440-22-4	0.836	0.05		538	
	non noble metal	tin	7440-31-5	0.669	0.04		431	
	non noble metal	lead	7439-92-1	31.925	2.06	2.15	20564	21533
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.84	6.85	68412	68502
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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